

## Synthesis of epitaxial graphene on SiC for electronic applications

**Alberto García-García**<sup>1,2\*</sup>, Ana Ballestar<sup>1</sup>, Luis Serrano-Ramón<sup>1</sup>, Gemma Rius<sup>2</sup>,  
Manuel Ricardo Ibarra<sup>3</sup>, José María De Teresa<sup>3,4</sup>, Philippe Godignon<sup>2</sup>

<sup>1</sup> Graphene Nanotech (GPNT), CEMINEM, Zaragoza, Spain

<sup>2</sup> Instituto de Microelectrónica de Barcelona, CNM-CSIC, Barcelona, Spain

<sup>3</sup> Laboratorio de Microscopías Avanzadas (LMA), Instituto de Nanociencia de Aragón (INA), Departamento de Física de la Materia Condensada, University of Zaragoza, Zaragoza, Spain

<sup>4</sup> Instituto de Ciencia de Materiales de Aragón (ICMA), CSIC-University of Zaragoza, Zaragoza, Spain

\* [alberto@gpnt.es](mailto:alberto@gpnt.es)

Decomposition of silicon carbide (SiC) at high temperatures [1] is an effective route to synthesize wafer-scale single-crystal graphene [2]. The underlying process in the surface graphitization of SiC is the preferential sublimation of Si atoms at high temperature ( $T$ ), typically above  $T=1500^{\circ}\text{C}$ . Graphene nucleation, coupling with the buffer layer and morphology are strongly influenced by the experimental conditions and the intrinsic properties of the substrates, such as polar face, quality, miscut angle and doping. In this talk we will summarize several of our recent results for producing graphene on SiC based on previous research [2, 3]. Furthermore, we will present technological solutions such as ion implantation (see Figure 1) for bottom gating, opening new avenues towards the fabrication of graphene-based devices.

### Figures

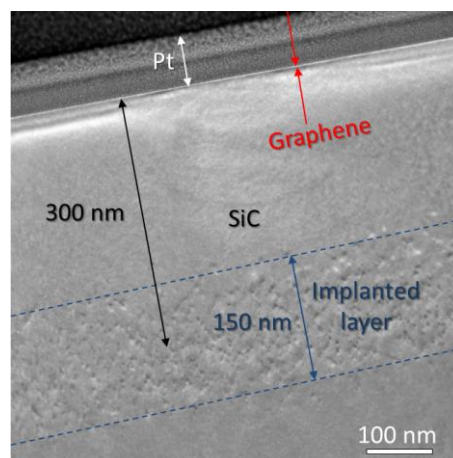


Figure 1: Cross-sectional transmission electron microscopy micrograph of a selected SiC sample covered with graphene, showing a buried conductive layer fabricated via ion (nitrogen) implantation.

### References

- [1] D. V. Badami. *Carbon* **3**, 53 (1965)
- [2] N. Camara et al. *J. Phys. D: Appl. Phys.* **43**, 374011 (2010)
- [3] N. Srivastava et al. *J. Phys. D: Appl. Phys.* **45**, 154001 (2012)